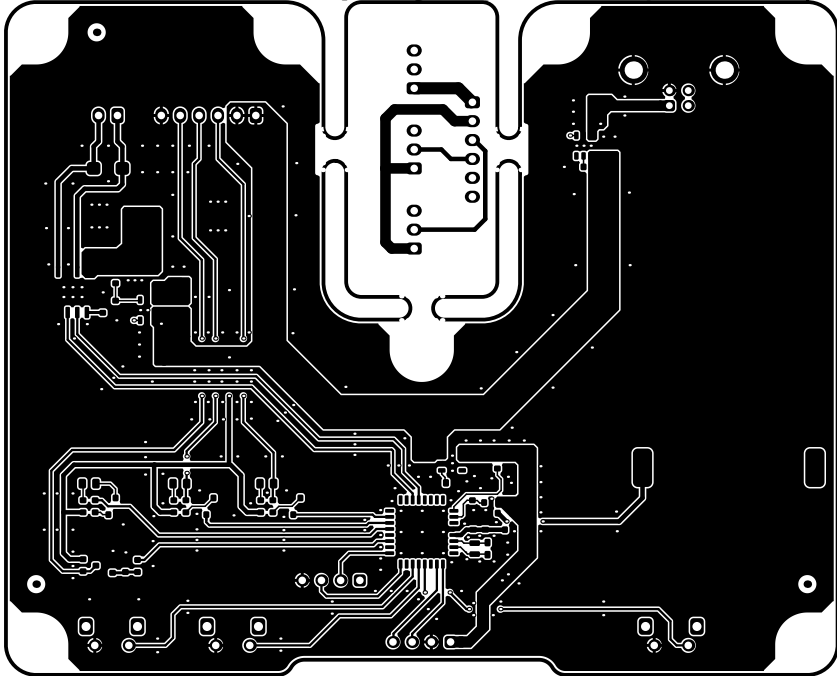
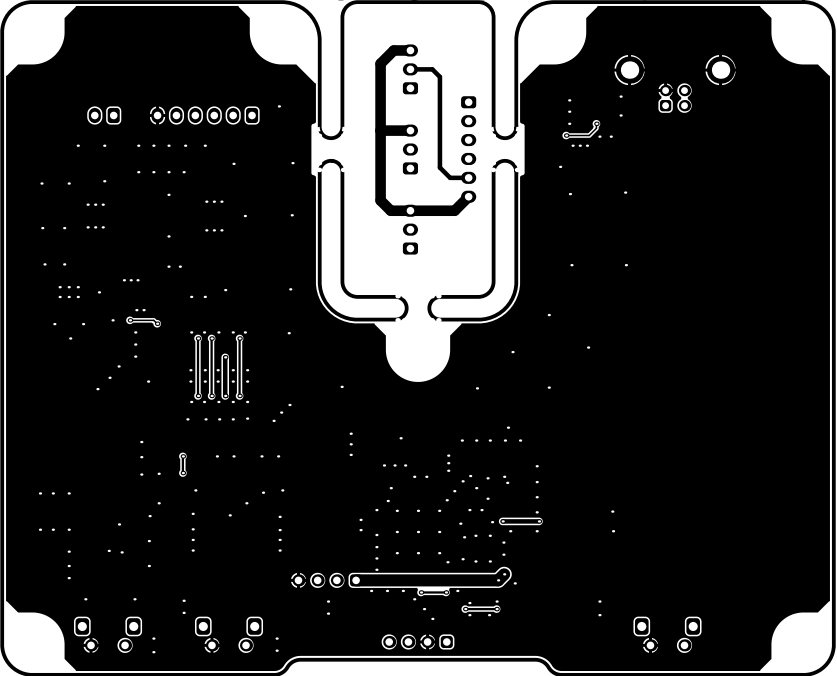


SOLC5-G031-B - Top Layer (Scale 1:1)



SOLC5-G031-B - Top Layer (Scale 1:1)



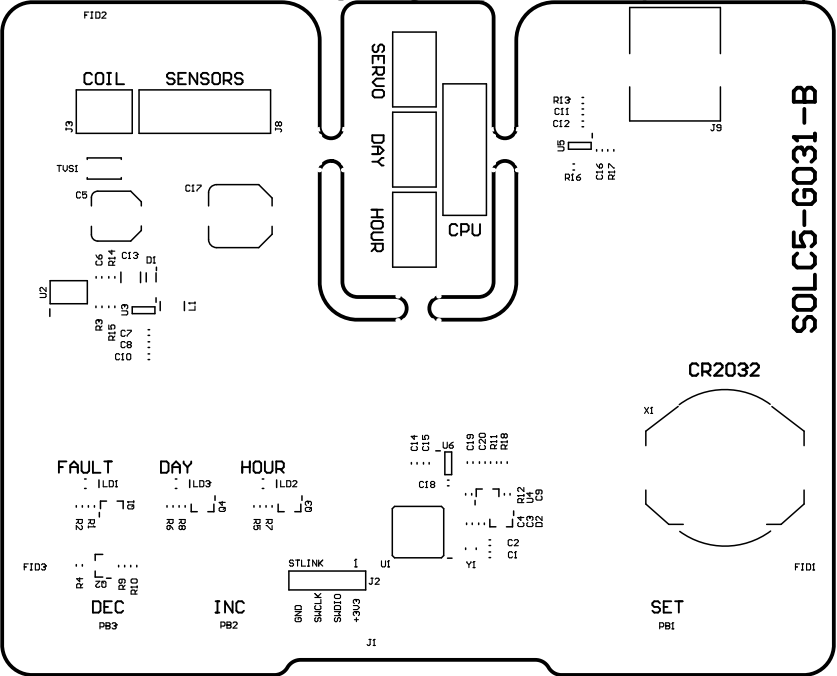
Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.0254mm	SM-001	Solder Mask	GTS
PbSn	Top Copper Plating	0.0200mm		Surface Finish	
CF-003	Top Layer	0.0180mm		Signal	GTL
Core		1.5000mm	FR-4 TG140	Dielectric	
CF-003	Bottom Layer	0.0180mm		Signal	GBL
PbSn	Bottom Copper Plating	0.0200mm		Surface Finish	
Surface Material	Bottom Solder	0.0254mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.6268mm					

Board Specification

Minimum Track	0.2 mm	Solder Mask Color	Blue
Minimum Gap	0.2 mm	Silkscreen	White
VIA Process	Tented	Board Finish	HASL - LEAD

SOLC5-G031-B - Top Layer (Scale 1:1)



Project: **Solari Cifra 5 Control STM32-G031K8**

Revision: **B**



Title: **Board Specifications**

Sheet: 1 of 2

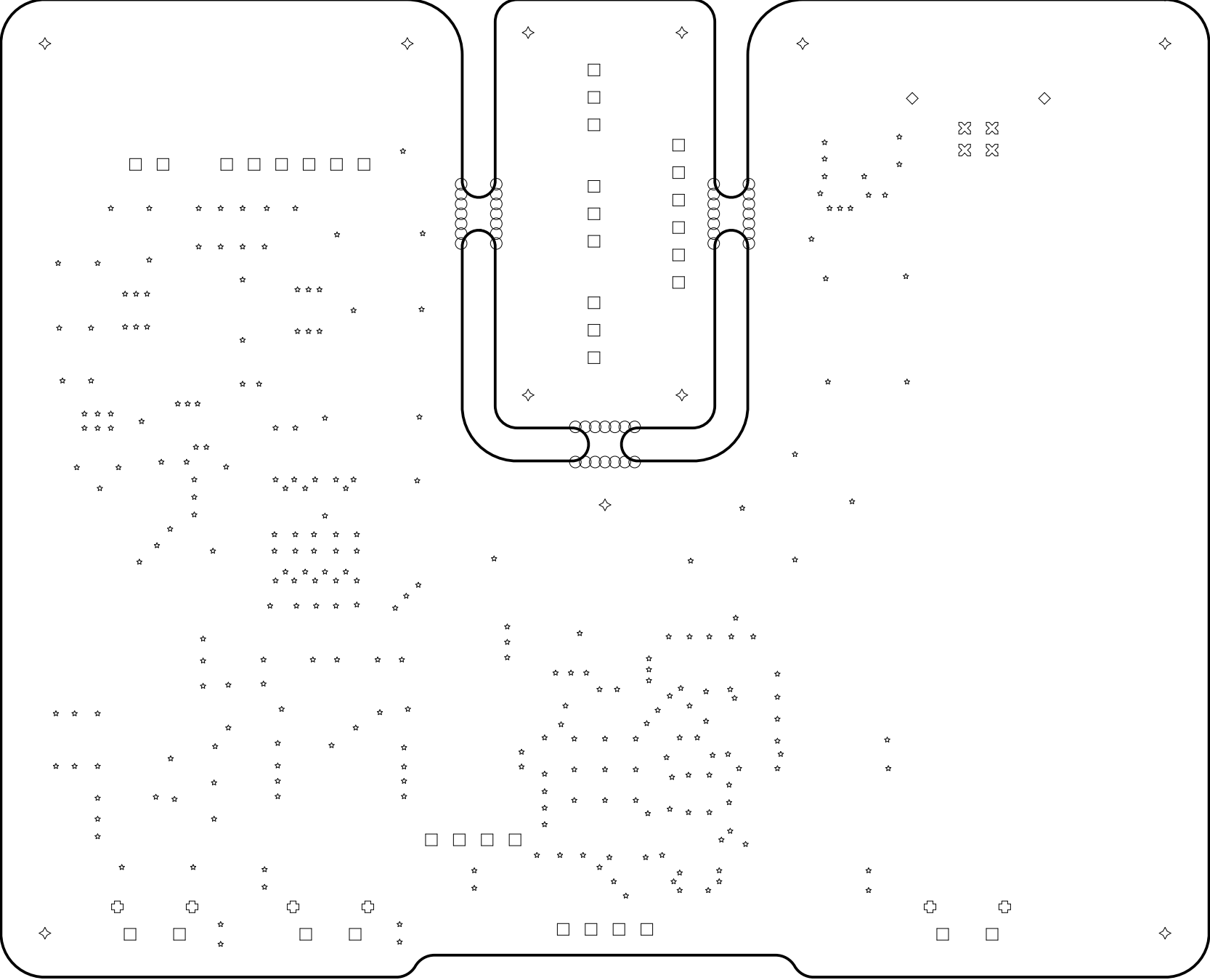
Date: **July-01-2021**

Author: **Alfredo Cortellini**

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SOLC5-G031-B - Drill Drawing View (Scale 2:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Via / Pad	Hole Tolerance
☆	265	0.30mm	Plated	Round	Via	
○	42	0.60mm	Non-Plated	Round	Pad	
⊗	4	0.90mm	Plated	Round	Pad	
□	37	1.00mm	Plated	Round	Pad	
⊕	6	1.20mm	Plated	Round	Pad	
◇	2	2.30mm	Plated	Round	Pad	
◆	11	3.20mm	Non-Plated	Round	Pad	
367 Total						

Project: **Solari Cifra 5 Control STM32-G031K8**

Revision: **B**

Title: **Board Specifications**

Sheet: 2 of 2

Date: **July-01-2021**

Author: **Alfredo Cortellini**

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